



承认书

SPECIFICATION FOR APPROVAL

| | | |
|-------------------------------|---|------------------------|
| 客户 Customer | : | |
| 客户批号 Customer Part No. | : | |
| 并日型号 Bingri Part No. | : | Z4545P24J0Y000 |
| 制作人 Prepared By | : | 日期 Time: 2020/01/8 |
| 审核 Checkedy | : | 日期 Time: 2020/01/08 |
| 客户回签 Customer Comfirmation | : | 日期 Time: |

并日电子科技（深圳）有限公司

BING RI ELECTRONIC TECHNOLOGY (S.Z.) CO.,LTD

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客户意见栏 (Customer' S Proposal)

Approve 承认 (请于认可栏中签名) Disagree 不同意

Reason 原因: _____

版本 (Version): 1.3



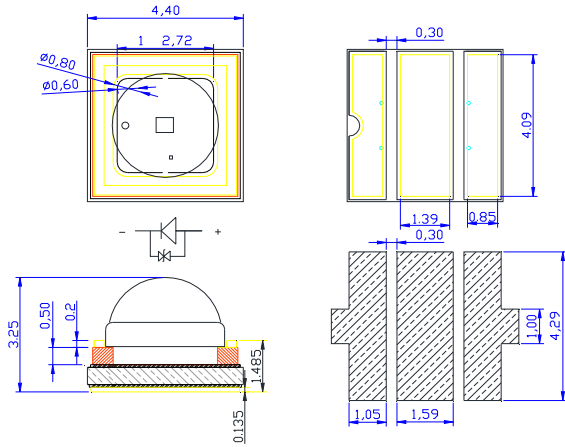
● **Features:**

1. Emitted Color: UVC
2. Lens Appearance: Clean quartz lens
3. 4.45x4.45x3.25mm standard package.
4. Suitable for all SMT assembly methods.
5. Compatible with infrared and vapor phase reflow solder process.
6. Compatible with automatic placement equipment.
7. This product doesn't contain restriction Substance, comply ROHS standard.

● **Applications:**

1. Sterilize

● **Package Dimensions:**



NOTES:

1. All dimensions are in millimeters.
2. Tolerance is ± 0.10 mm unless otherwise specified.
3. Specifications are subject to change without notice.

● **Part Numbering System:**

| | | | | | | |
|----------|-------------|-----------|-----------|----------|----------|------------|
| <u>Z</u> | <u>4545</u> | <u>P2</u> | <u>4J</u> | <u>0</u> | <u>Y</u> | <u>000</u> |
| (1) | (2) | (3) | (4) | (5) | (6) | (7) |

- (1) B: Substrate code
- (2) Package type: 4545
- (3) LED Color: P2 means UVC segment
- (4) Chip code
- (5) 0: CRI not required
- (6) Y: Type of adhesives
- (7) 000: Color bin



ATTENTION
 OBSERVE PRECAUTIONS
 FOR HANDLING
 ELECTROSTATIC
 DISCHARGE
 SENSITIVE
 DEVICES



● **Absolute Maximum Ratings (Ta=25°C)**

| Item | Symbol | Value | Unit |
|------------------------------------|--------|-------------|------|
| Power Dissipation | PD | 2.2 | W |
| DC Forward Current | IF | 200 | mA |
| Single Chip Pulsed Forward Current | IFP | 300※ | mA |
| Reverse Voltage | VR | 5 | V |
| Operating Temperature | Topr | -30 ~ +80■ | °C |
| Storage Temperature | Tstg | -40 ~ +120 | °C |
| Soldering Temperature | Tsol | 260for5sec△ | °C |

※Duty 1/10, Pulse Width 0.1ms.

△Soldering time max 10sec

■please refer to IF-Ta diagram of curves for the temperature during application

● **UVC parameter**

200mA

| Parameter | Symbol | Value | | | Unit | Test condition |
|-----------------|--------|-------|------|-----|------|----------------|
| | | Min. | Typ. | Max | | |
| Forward Voltage | Vf | - | 6.2 | - | V | If=200mA |
| Reverse Current | Ir | - | - | 10 | μ A | Vr=5V |
| Viewing angle | 2θ1/2 | - | 60 | - | Deg | If=200mA |
| Peak Wavelength | λp | 270 | 275 | 280 | nm | If=200mA |
| Luminous Power | Po | 25 | 30 | 35 | mw | If=200mA |



● **Soldering :**

1. Manual Soldering

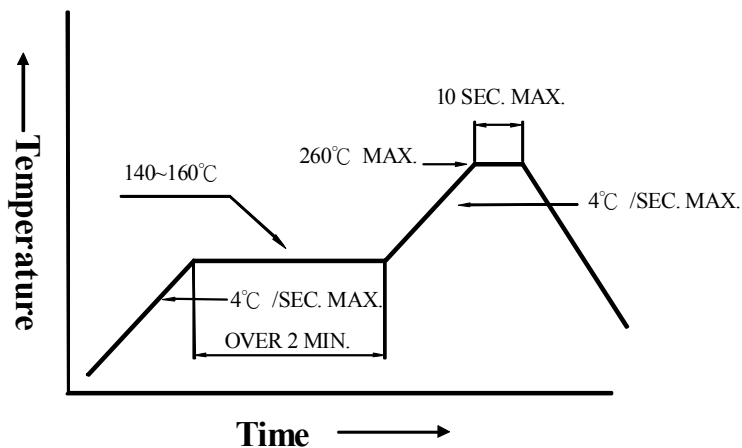
The temperature of the iron tip should not be higher than 350°C and Soldering time to be within 3 seconds per solder-pad.

2. Reflow Soldering

Preheating : 140°C~160°C±5°C, within 2 minutes.

Operation heating : 260°C (Max.) within 10 seconds. (Max)

Gradual Cooling (Avoid quenching).



● **Storage:**

In order to avoid the absorption of moisture, it is recommended to solder BINGRI LEDs as soon as possible after unpacking the sealed envelope.

If the envelope is still packed, to store it in the environment as following:

- (1) Temperature : 5°C-30°C(41°F) Humidity : RH 60 % Max.
- (2) After this bag is opened, devices that will be applied to infrared reflow, vapor-phase reflow, or equivalent soldering process must be:
 - a. Completed within 168 hours.
 - b. Stored at less than 30% RH.
- (3) Devices require baking before mounting, if:
 - (2) a or (2) b is not met.
- (4) If baking is required, devices must be baked under below conditions:
48 hours at 60°C±3°C.